

Carsem - Suzhou



Carsem Semiconductor (Suzhou) Co. Ltd., No.408, Shen Hu Road In District 2
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Carsem-Suzhou Ltd. was formed in March 2002 and is located in the province of Jiangsu 50 miles (80 km) west of Shanghai. The factory is 172K sq. ft. (16K sq. m.) and is on 645K sq. ft (60K sq. m.) of land in the Suzhou Industrial Park. Construction started in April 2003 and was completed in January 2004. Initial customer qualifications were completed during the second quarter of 2004 and the factory began shipping production volumes in July 2004.

The factory currently provides full turnkey assembly and test services for the production of the entire range of MLPQ (Quad) and MLPD (Dual) packages, which is a saw-singulated version of QFN & SON compliant packages per JEDEC's M0220 and M0229 standard's.

The portfolio of MLP package body sizes range from 2x2 mm to 9x9 mm with the nominal thickness ranging from 0.75 mm to 0.9 mm. Lead counts range from 4 to 64 in pitches between 0.5 mm to 1.27 mm and custom sizes are available upon request.

Services and process options include Wafer back-grinding, Wafer probe, Wafer scribing of GaAs wafers, Assembly, Final test, Tape and reel and Drop ship. Green/lead-free solutions are also available.

Malaysia

Ipoh (M-site)
tel: 60-5-3123333
fax: 60-5-3125333

Malaysia

Ipoh (S-site)
tel: 60-5-5262333
fax: 60-5-5265333

China

Suzhou
tel: 86-512-6258-8883
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Europe

UK
tel: 44-1793-853888
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USA

Silicon Valley
tel: 831-438-6861
fax: 831-438-6863

USA

Los Angeles
tel: 626-854-0939
fax: 626-854-9139

USA

Dallas
tel: 972-580-1706
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